

256K (32K x 8) Static RAM

Features

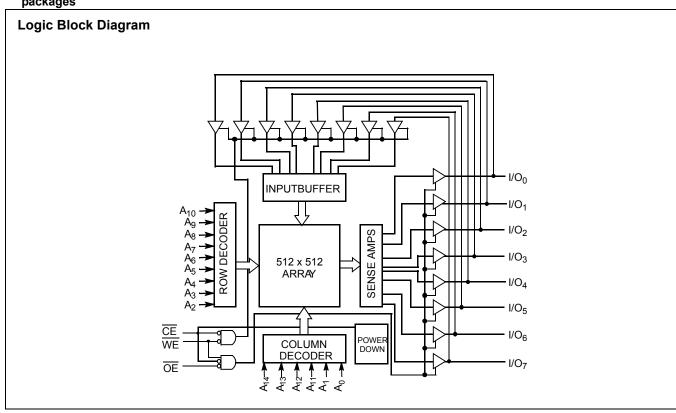
- Temperature Ranges
 - Commercial: 0°C to 70°C
 Industrial: -40°C to 85°C
 Automotive: -40°C to 125°C
- High speed: 55 ns and 70 ns
- Voltage range: 4.5V-5.5V operation
- Low active power (70 ns, LL version, Com'l and Ind'l)
 - —275 mW (max.)
- Low standby power (70 ns, LL version, Com'l and Ind'l)
 —28 μW (max.)
- Easy memory expansion with $\overline{\text{CE}}$ and $\overline{\text{OE}}$ features
- · TTL-compatible inputs and outputs
- · Automatic power-down when deselected
- · CMOS for optimum speed/power
- Package available in a standard 450-mil-wide (300-mil body width) 28-lead narrow SOIC, 28-lead TSOP-1, 28-lead reverse TSOP-1, and 600-mil 28-lead PDIP packages

Functional Description[1]

The CY62256 is a high-performance CMOS static RAM organized as 32K words by 8 bits. Easy memory expansion is provided by an active LOW chip enable (CE) and active LOW output enable (OE) and three-state drivers. This device has an automatic power-down feature, reducing the power consumption by 99.9% when deselected.

An active LOW write enable signal (WE) controls the writing/reading operation of the memory. When $\overline{\text{CE}}$ and $\overline{\text{WE}}$ inputs are both LOW, data on the eight data input/output pins (I/O $_0$ through I/O $_7$) is written into the memory location addressed by the address present on the address pins (A $_0$ through A $_{14}$). Reading the device is accomplished by selecting the device and enabling the outputs, CE and OE active LOW, while WE remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins are present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable (WE) is HIGH.



Note:

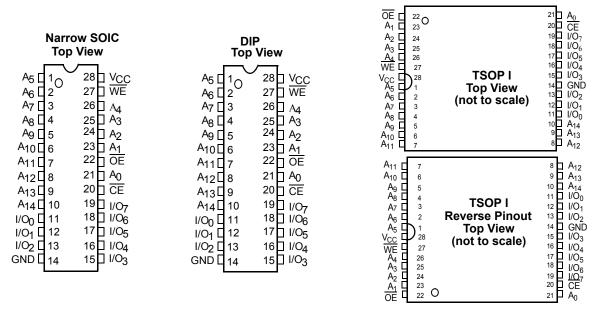
1. For best practice recommendations, please refer to the Cypress application note "System Design Guidelines" on http://www.cypress.com.



Product Portfolio

| | | | | | | | Power Dis | sipation | |
|-----------|---------------|------|-------------------------|------------|-------|-----------------------------|-----------------------------|-----------------------------|------|
| | | | V _{CC} Range (| V) | Speed | Operat (m | ing, I _{CC} nA) | Standb (μ/ | |
| Product | | Min. | Тур. ^[2] | Max. | (ns) | Typ . ^[2] | Max. | Typ . ^[2] | Max. |
| CY62256 | Commercial | 4.5 | 5.0 | 5.5 | 70 | 28 | 55 | 1 | 5 |
| CY62256L | Com'l / Ind'l | | | | 55/70 | 25 | 50 | 2 | 50 |
| CY62256LL | Commercial | | | | 70 | 25 | 50 | 0.1 | 5 |
| CY62256LL | Industrial | | | | 55/70 | 25 | 50 | 0.1 | 10 |
| CY62256LL | Automotive | 1 | | | 55 | 25 | 50 | 0.1 | 15 |

Pin Configurations



Pin Definitions

| Pin Number | Туре | Description | | | |
|-----------------|---------------|--|--|--|--|
| 1-10, 21, 23-26 | Input | A ₀ -A ₁₄ . Address Inputs | | | |
| 11-13, 15-19, | Input/Output | O ₀ -I/O ₇ . Data lines. Used as input or output lines depending on operation | | | |
| 27 | Input/Control | TE . When selected LOW, a WRITE is conducted. When selected HIGH, a READ is onducted | | | |
| 20 | Input/Control | CE. When LOW, selects the chip. When HIGH, deselects the chip | | | |
| 22 | Input/Control | OE . Output Enable. Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, I/O pins are three-stated, and act as input data pins | | | |
| 14 | Ground | GND. Ground for the device | | | |
| 28 | Power Supply | Vcc. Power supply for the device | | | |

Typical specifications are the mean values measured over a large sample size across normal production process variations and are taken at nominal conditions
(T_A = 25°C, V_{CC}). Parameters are guaranteed by design and characterization, and not 100% tested.



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.) Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied-55°C to +125°C Supply Voltage to Ground Potential (Pin 28 to Pin 14)-0.5V to +7.0V DC Voltage Applied to Outputs in High-Z State $^{[3]}$ -0.5V to V $_{\rm CC}$ + 0.5V

| Output Current into Outputs (LOW) | 20 mA |
|--|-----------|
| Static Discharge Voltage(per MIL-STD-883, Method 3015) | . > 2001V |
| Latch-up Current | > 200 mA |

Operating Range

| Range | Ambient Temperature (T _A) ^[4] | V _{cc} |
|------------|--|-----------------|
| Commercial | 0°C to +70°C | 5V ± 10% |
| Industrial | -40°C to +85°C | 5V ± 10% |
| Automotive | –40°C to +125°C | 5V ± 10% |

Electrical Characteristics Over the Operating Range

DC Input Voltage^[3].....–0.5V to V_{CC} + 0.5V

| | | | | CY62256-55 | | | С | | | |
|------------------|--|---|-----------------|------------|---------------------|--------------------------|------|---------------------|--------------------------|------|
| Parameter | Description | Test Conditions | Test Conditions | | Typ. ^[2] | Max. | Min. | Typ. ^[2] | Max. | Unit |
| V _{OH} | Output HIGH Voltage | V _{CC} = Min., I _{OH} = -1.0 m/ | Ą | 2.4 | | | 2.4 | | | V |
| V _{OL} | Output LOW Voltage | V _{CC} = Min., I _{OL} = 2.1 mA | | | | 0.4 | | | 0.4 | V |
| V _{IH} | Input HIGH Voltage | | | 2.2 | | V _{CC} +0.5V | 2.2 | | V _{CC} +0.5V | V |
| V _{IL} | Input LOW Voltage | | | -0.5 | | 8.0 | -0.5 | | 0.8 | V |
| I _{IX} | Input Leakage Current | $GND \le V_1 \le V_{CC}$ | | -0.5 | | +0.5 | -0.5 | | +0.5 | μΑ |
| I _{OZ} | Output Leakage Current | GND \leq V _O \leq V _{CC} , Output D | Disabled | -0.5 | | +0.5 | -0.5 | | +0.5 | μΑ |
| I _{CC} | V _{CC} Operating Supply Current | V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = 1/ t_{RC} | | | 28 | 55 | | 28 | 55 | mA |
| | | | L | | 25 | 50 | | 25 | 50 | mA |
| | | | LL | | 25 | 50 | | 25 | 50 | mA |
| I _{SB1} | Automatic CE | Max. V_{CC} , $\overline{CE} \ge V_{IH}$, | | | 0.5 | 2 | | 0.5 | 2 | mA |
| | Power-down Current— TTL Inputs | $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$, $f = f_{MAX}$ | L | | 0.4 | 0.6 | | 0.4 | 0.6 | mA |
| | 112 mpato | † _{MAX} | LL | | 0.3 | 0.5 | | 0.3 | 0.5 | mA |
| I _{SB2} | Automatic CE | Max. V_{CC} , $\overline{CE} \ge V_{CC} - 0.3V$ | | | 1 | 5 | | 1 | 5 | mA |
| | Power-down Current— CMOS Inputs | $V_{IN} \ge V_{CC} - 0.3V$, or $V_{IN} \le 0.3V$. f = 0 | L | | 2 | 50 | | 2 | 50 | μΑ |
| | OMOO IIIpato | 0.0 4, 1 – 0 | LL | | 0.1 | 5 | | 0.1 | 5 | μА |
| | | | LL - Ind'l | | 0.1 | 10 | | 0.1 | 10 | μА |
| | | | LL - Auto | | 0.1 | 15 | | | | μА |

Capacitance^[5]

| Parameter | Description | Test Conditions | Max. | Unit |
|------------------|--------------------|-----------------------------------|------|------|
| C _{IN} | Input Capacitance | T _A = 25°C, f = 1 MHz, | 6 | pF |
| C _{OUT} | Output Capacitance | V _{CC} = 5.0V | 8 | pF |

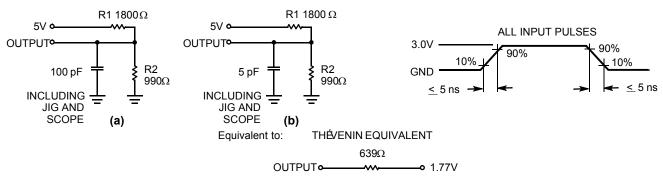
- 3. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
- 4. T_A is the "Instant-On" case temperature.
 5. Tested initially and after any design or process changes that may affect these parameters.



Thermal Resistance

| Description | Test Conditions | Symbol | DIP | SOIC | TSOP | RTSOP | Unit |
|--|---|-------------------|-------|-------|-------|-------|------|
| [6] | Still Air, soldered on a 4.25 x 1.125 inch, 4-layer printed circuit board | Θ_{JA} | 75.61 | 76.56 | 93.89 | 93.89 | °C/W |
| Thermal Resistance (Junction to Case) ^[5] | | $\Theta_{\sf JC}$ | 43.12 | 36.07 | 24.64 | 24.64 | °C/W |

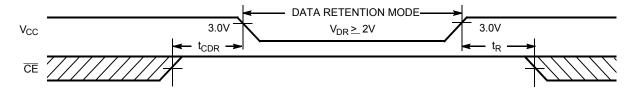
AC Test Loads and Waveforms



Data Retention Characteristics

| Parameter | Description | | Conditions ^[6] | Min. | Typ. ^[2] | Max. | Unit |
|---------------------------------|--------------------------------------|------------|---|-----------------|---------------------|------|------|
| V_{DR} | V _{CC} for Data Retention | | | 2.0 | | | V |
| I _{CCDR} | Data Retention Current | L | $V_{CC} = 3.0V, \overline{CE} \ge V_{CC} - 0.3V,$ | | 2 | 50 | μΑ |
| | | LL | $V_{IN} \ge V_{CC} - 0.3V$, or $V_{IN} \le 0.3V$ | | 0.1 | 5 | μΑ |
| | | LL - Ind'l | | | 0.1 | 10 | μΑ |
| | | LL - Auto | | | 0.1 | 10 | μΑ |
| t _{CDR} ^[5] | Chip Deselect to Data Retention Time | | | 0 | | | ns |
| t _R ^[5] | Operation Recovery Time | | | t _{RC} | | | ns |

Data Retention Waveform



Notes:

6. No input may exceed V_{CC} + 0.5V.

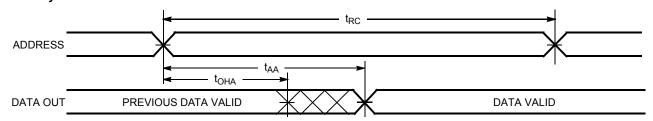


Switching Characteristics Over the Operating Range^[7]

| | | CY62 | 256–55 | CY62 | | |
|---------------------------------|-------------------------------------|----------|--------|------|------|------|
| Parameter | Description | Min. | Max. | Min. | Max. | Unit |
| Read Cycle | | ' | | 1. | | • |
| t _{RC} | Read Cycle Time | 55 | | 70 | | ns |
| t _{AA} | Address to Data Valid | | 55 | | 70 | ns |
| t _{OHA} | Data Hold from Address Change | 5 | | 5 | | ns |
| t _{ACE} | CE LOW to Data Valid | | 55 | | 70 | ns |
| t _{DOE} | OE LOW to Data Valid | | 25 | | 35 | ns |
| t _{LZOE} | OE LOW to Low-Z ^[8] | 5 | | 5 | | ns |
| t _{HZOE} | OE HIGH to High-Z ^[8, 9] | | 20 | | 25 | ns |
| t _{LZCE} | CE LOW to Low-Z ^[8] | 5 | | 5 | | ns |
| t _{HZCE} | CE HIGH to High-Z ^[8, 9] | | 20 | | 25 | ns |
| t _{PU} | CE LOW to Power-up | 0 | | 0 | | ns |
| t _{PD} | CE HIGH to Power-down | | 55 | | 70 | ns |
| Write Cycle ^[10, 11] | | • | | | | |
| t _{WC} | Write Cycle Time | 55 | | 70 | | ns |
| t _{SCE} | CE LOW to Write End | 45 | | 60 | | ns |
| t _{AW} | Address Set-up to Write End | 45 | | 60 | | ns |
| t _{HA} | Address Hold from Write End | 0 | | 0 | | ns |
| t _{SA} | Address Set-up to Write Start | 0 | | 0 | | ns |
| t _{PWE} | WE Pulse Width | 40 | | 50 | | ns |
| t _{SD} | Data Set-up to Write End | 25 | | 30 | | ns |
| t _{HD} | Data Hold from Write End | 0 | | 0 | | ns |
| t _{HZWE} | WE LOW to High-Z ^[8, 9] | | 20 | | 25 | ns |
| t _{LZWE} | WE HIGH to Low-Z ^[8] | 5 | | 5 | | ns |
| t _{HZWE} | _ | 5 | 20 | 5 | 25 | |

Switching Waveforms

Read Cycle No. 1^[12, 13]

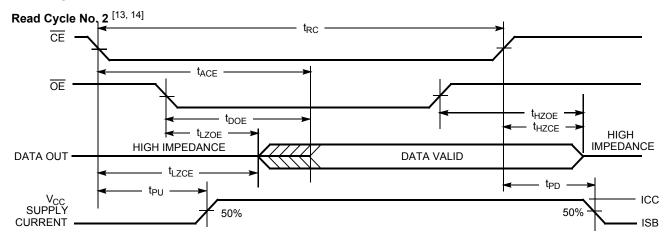


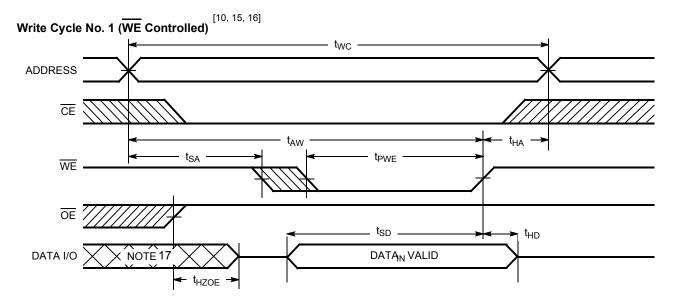
- 7. Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified

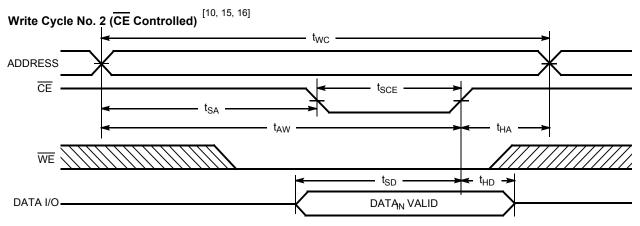
- Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified loL/l_{OH} and 100-pF load capacitance.
 At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZCE}, and t_{HZWE} is less than t_{LZWE} for any given device.
 t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with C_L = 5 pF as in (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
 The internal Write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a Write and either signal can terminate a Write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the Write.
 The minimum Write cycle time for Write cycle #3 (WE controlled, OE LOW) is the sum of t_{HZWE} and t_{SD}
- 12. Device is continuously selected. \overline{OE} , $\overline{CE} = V_{IL}$.
- 13. WE is HIGH for Read cycle.



Switching Waveforms (continued)





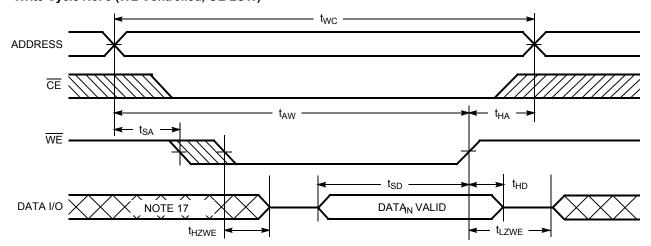


- Address valid prior to or coinc<u>ide</u>nt with CE transition LOW.
 Data I/O is high impedance if OE = V_{IH}.
 If CE goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.
 During this period, the I/Os are in output state and input signals should not be applied.



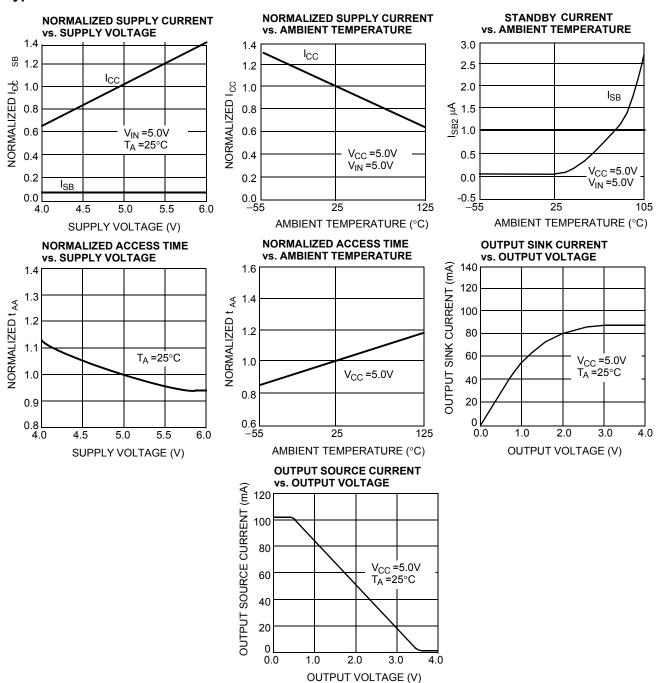
Switching Waveforms (continued)

Write Cycle No. 3 (WE Controlled, OE LOW) [11, 16]



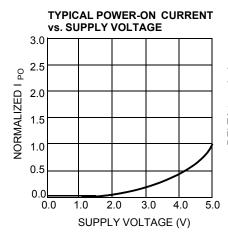


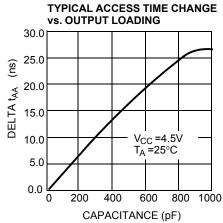
Typical DC and AC Characteristics

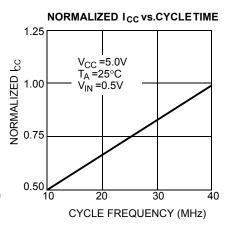




Typical DC and AC Characteristics (continued)







Truth Table

| CE | WE | OE | Inputs/Outputs | Mode | Power |
|----|----|----|----------------|---------------------|----------------------------|
| Н | Х | Х | High-Z | Deselect/Power-down | Standby (I _{SB}) |
| L | Н | L | Data Out | Read | Active (I _{CC}) |
| L | L | Х | Data In | Write | Active (I _{CC}) |
| L | Н | Н | High-Z | Output Disabled | Active (I _{CC}) |

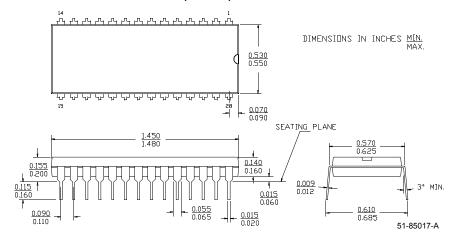
Ordering Information

| Speed (ns) | Ordering Code | Package Name | Package Type | Operating Range |
|------------|-----------------|-----------------|--|--------------------|
| 55 | CY62256LL-55SNI | SN28 | 28-lead (300-Mil Narrow Body) Narrow SOIC | Industrial |
| | CY62256LL-55ZI | Z28 | 28-lead Thin Small Outline Package | |
| | CY62256LL-55SNE | SN28 | 28-lead (300-Mil Narrow Body) Narrow SOIC | Automotive |
| | CY62256LL-55ZE | Z28 | 28-lead Thin Small Outline Package | |
| | CY62256LL-55ZRE | ZR28 | 28-lead Reverse Thin Small Outline Package | |
| 70 | CY62256-70SNC | SN28 | 28-lead (300-Mil Narrow Body) Narrow SOIC | Commercial |
| | CY62256L-70SNC | | | |
| | CY62256LL-70SNC | | | |
| | CY62256L-70SNI | | | Industrial |
| | CY62256LL-70SNI | | | |
| | CY62256LL-70ZC | Z28 | 28-lead Thin Small Outline Package | Commercial |
| | CY62256LL-70ZI | Z28 | | Industrial |
| | CY62256-70PC | P15 | 28-lead (600-Mil) Molded DIP | Commercial |
| | CY62256L-70PC | P15 | | |
| | CY62256LL-70PC | P15 | | |
| | CY62256LL-70ZRI | ZR28 | 28-lead Reverse Thin Small Outline Package | Industrial |

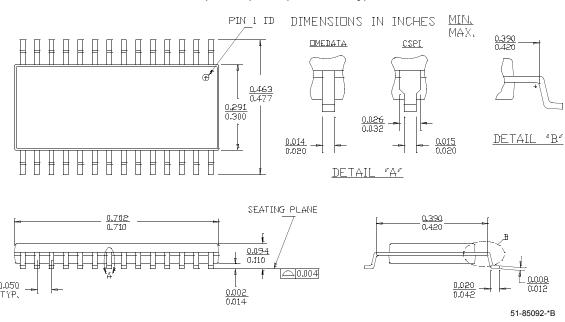


Package Diagrams

28-lead (600-mil) Molded DIP P15



28-lead (300-mil) SNC (Narrow Body) SN28

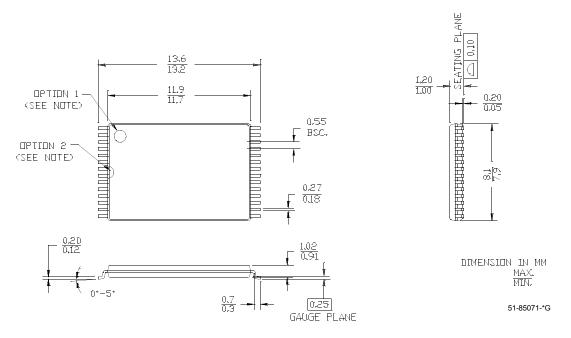




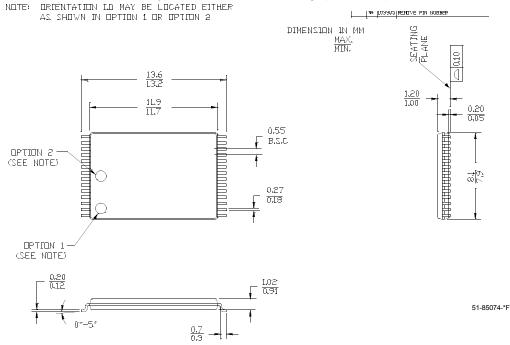
Package Diagrams (continued)

28-lead Thin Small Outline Package Type 1 (8 x 13.4 mm) Z28

NOTE: ORIENTATION IND MAY BE LOCATED EITHER AS SHOWN IN OPTION 1 OR OPTION 2



28-lead Reverse Type 1 Thin Small Outline Package (8 x 13.4 mm) ZR28



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| | Document Title: CY62256 256K (32K x 8) Static RAM Document Number: 38-05248 | | | | | | | | | |
|------|--|---------------|--------------------|--|--|--|--|--|--|--|
| REV. | ECN NO. | Issue Date | Orig. of Change | Description of Change | | | | | | |
| ** | 113454 | 03/06/02 | MGN | Change from Spec number: 38-00455 to 38-05248 Remove obsolete parts from ordering info, standardize format | | | | | | |
| *A | 115227 | 05/23/02 | GBI | Changed SN Package Diagram | | | | | | |
| *B | 116506 | 09/04/02 | GBI | Added footnote 1. Corrected package description in Ordering Information table | | | | | | |
| *C | 238448 | See ECN | AJU | Added Automotive product information | | | | | | |